

Title (en)

CAVITY FILLED METAL ELECTRONIC PACKAGE

Title (de)

METALLGEFÜLLTER HOHLRAUM FÜR ELEKTRONISCHE PACKUNG

Title (fr)

BOITIER ELECTRONIQUE METALLIQUE A CAVITE REMPLIE

Publication

**EP 0754350 A4 19981007 (EN)**

Application

**EP 95913778 A 19950320**

Priority

- US 9503468 W 19950320
- US 22320794 A 19940405

Abstract (en)

[origin: WO9527308A1] There is provided an electronic package (70) where the package components (52, 54) define a cavity (56). A semiconductor device (16) and a portion (18) of a leadframe (20) occupy part of the cavity (56). Substantially the remainder of the cavity (56) is filled with a polymer (26) so that an outermost surface (74) of the polymer (26) is coplanar with a surface (76) of one of the package components (54).

IPC 1-7

**H01L 23/02**; **H01L 23/28**

IPC 8 full level

**H01L 23/28** (2006.01); **H01L 21/56** (2006.01); **H01L 23/04** (2006.01); **H01L 23/24** (2006.01); **H01L 23/29** (2006.01)

CPC (source: EP)

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Citation (search report)

- [PX] WO 9409512 A1 19940428 - OLIN CORP [US]
- [XA] EP 0421005 A2 19910410 - OLIN CORP [US]
- [A] US 5134462 A 19920728 - FREYMAN BRUCE J [US], et al
- [A] WO 9220096 A1 19921112 - SENSOROR AS [NO]
- [PXPA] HOFFMAN P ET AL: "DEVELOPMENT OF A HIGH PERFORMANCE TQFP PACKAGE", 1 May 1994, PROCEEDINGS OF THE ELECTRONIC COMPONENTS AND TECHNOLOGY CONFERENCE, WASHINGTON, MAY 1 - 4, 1994, NR. CONF. 44, PAGE(S) 57 - 62, INSTITUTE OF ELECTRICAL AND ELECTRONICS ENGINEERS, XP000479146
- See references of WO 9527308A1

Designated contracting state (EPC)

DE GB

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**WO 9527308 A1 19951012**; AU 2103895 A 19951023; EP 0754350 A1 19970122; EP 0754350 A4 19981007; JP H09511617 A 19971118; TW 358238 B 19990511

DOCDB simple family (application)

**US 9503468 W 19950320**; AU 2103895 A 19950320; EP 95913778 A 19950320; JP 52572995 A 19950320; TW 84104480 A 19950505